



物質組成成份表
Materials Composition Declaration(MCD) Form

Part Number	uP1966EFBB
PKG Type	WLCSP

Materials Composition Spreadsheet						
Material	Weight(%)	Composition	CAS No.	Ratio(%)	Weight(mg)	PPM
Die	89.23%	Silicon	7440-21-3	100.0000%	1.4890000	892346.763
HD4100	1.25%	3,6,9-Trioxaundecamethylene dimethacrylate	109-17-1	16.3300%	0.0034032	2039.529
		Polyamic Acid Ester (Polyamic Acid Ester)	Trade secret	65.3000%	0.0136087	8155.617
		2-Hydroxyethyl methacrylate (2-Hydroxyethyl methacrylate)	868-77-9	2.0400%	0.0004251	254.785
		Aromatic Oxime (Aromatic Oxime)	Trade secret	16.3300%	0.0034032	2039.529
Cu 4N5	0.37%	Cu	7440-50-8	100.0000%	0.0061410	3680.256
Ti 4N5	0.09%	Ti	7440-32-6	100.0000%	0.0015525	930.402
MICROFAB CU MSA 200 MU	3.06%	Cu	7440-50-8	100.0000%	0.0511000	30623.855
Backside LC tape	5.99%	Acrylicester co-polymer	25038-59-9	100.0000%	0.1000000	59929.265
Total package weight(mg)					1.67	1000000.000